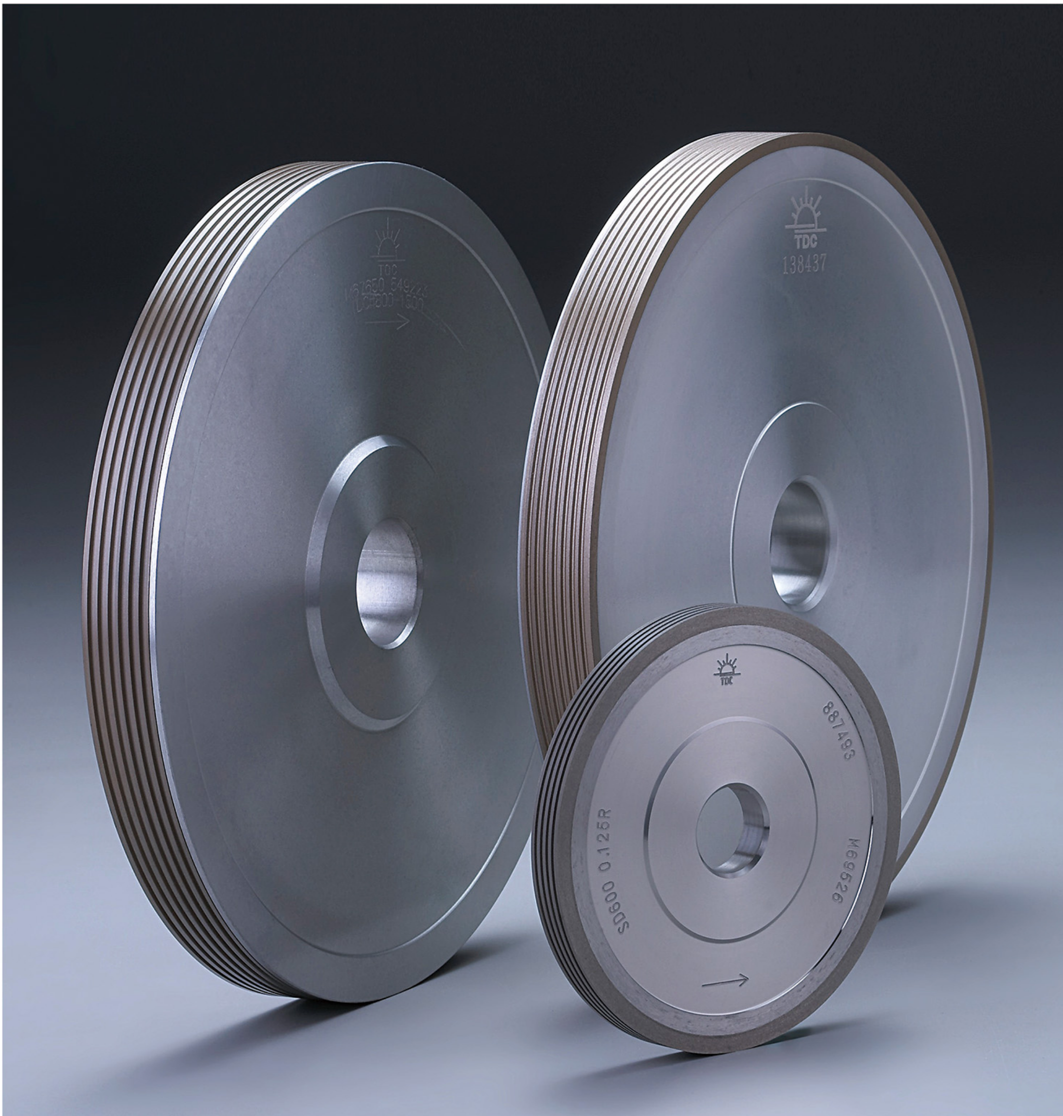
半導體晶圓金屬磨邊砂輪

Metal bond Edge Grinding Wheel for Semiconductor Wafer



適用晶圓種類：2“~12” 矽, 碳化矽, 砷化鎵, 鉭酸鋰, 藍寶石…等半導體晶圓
Suitable Semiconductor wafers: 2”~12” Silicon, SiC, GaAs, LT, Sapphire and so on

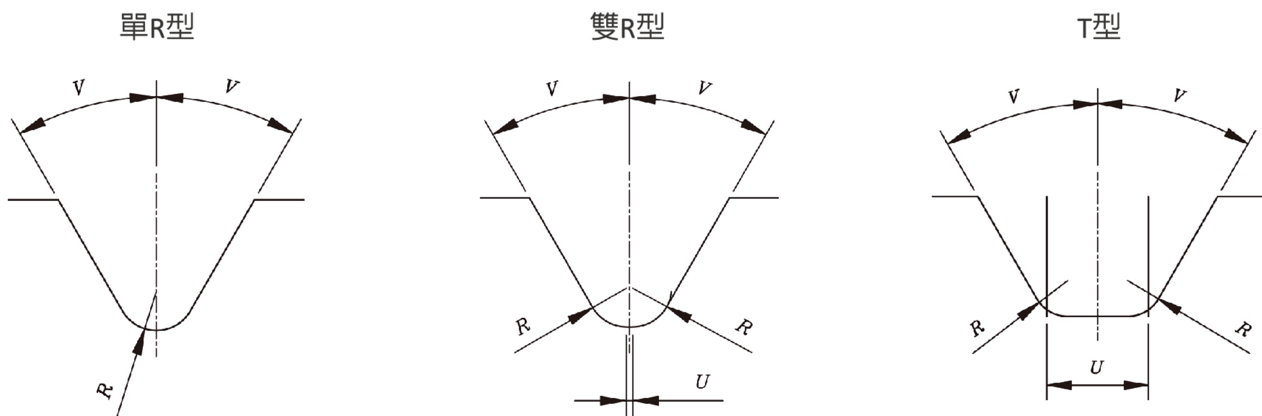
TDC
台灣鑽石工業股份有限公司
Taiwan Asahi Diamond Industrial Co., Ltd.

尺寸規格表 The Table of Sizes

工程 Process	粒度 Grit size	砂輪外徑 Wheel OD.	鑽石層厚度 Thickness of diamond layer	溝數 No. of grooves
粗磨 Rough	#400~800	ϕ 102, ϕ 202	2.5~5mm	1~10
細磨 Fine	#1000~3000			

能生產的詳細尺寸請向敝公司營業部門諮詢
Please contact our sales representatives for details on the sizes we can manufacture

溝型種類及尺寸精度 Groove Shape Type and Size Tolerance

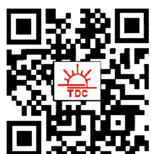


形狀精度 Shape accuracy	溝深 Depth of groove	角度V Angle	R
公差 Tolerance	±0.1mm	±20'	±0.01mm

加工參數及表現 Grinding Recipe and Performance

工程 Process	砂輪周速度 (m/min) Wheel rotation speed	進給速度 (mm/sec) Feed speed	晶圓面粗度 (µm) Roughness of wafer	壽命 Life
粗磨 Rough	1800~2500	10~30	Ra0.3 (#800)	>10,000pcs/G (102 ϕ , 6" silicon)
細磨 Fine			Ra0.15 (#1500)	

敝公司可根據客戶需求調配不同配方內容，詳細請向敝公司營業部門諮詢
Our company have different wheel recipe based on customer demand. Please contact our sales representatives for the details.



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